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Space product assurance - Design rules for printed circuit boards; English version
EN 16602-70-12:2016

Contents	Page
European foreword	12
Introduction	13
1 Scope	14
2 Normative references	15
3 Terms, definitions and abbreviated terms	16
3.1 Terms from other standards	16
3.2 Terms specific to the present standard	16
3.3 Abbreviated terms	24
4 Principles	26
4.1 Qualified PCBs	26
4.2 Manufacturing tolerances	26
4.3 Reliability of design	26
5 Design review and MRR	28
5.1 Overview	28
5.2 Documentation	28
6 General design and production requirements	30
6.1 Reliability of design	30
6.2 Choice of materials and build-up.....	30
6.2.1 Overview.....	30
6.2.2 Material selection.....	33
6.3 Selection of the PCB manufacturer	33
6.4 Traceability and marking	33
7 Rigid PCBs	34
7.1 PCB build-up	34
7.1.1 General.....	34
7.1.2 Copper styles.....	34
7.1.3 Dielectric thickness.....	36
7.2 PCB dimension.....	39

7.3	Thickness of PCB	39
7.3.1	General	39
7.3.2	Polyimide PCB	40
7.3.3	Epoxy PCB	40
7.3.4	Number of copper layers in PCB	40
7.3.5	Aspect ratio of vias	40
7.4	Track width and spacing	41
7.4.1	General	41
7.4.2	Manufacturing tolerances for width and spacing	41
7.4.3	External layers	42
7.4.4	Normal pitch tracks on internal layers	43
7.4.5	Fine pitch tracks on internal layers	44
7.4.6	Routing to AAD footprint on internal layers	45
7.5	Pad design	46
7.5.1	Non-functional pad removal	46
7.5.2	Pad dimensions	46
7.5.3	Non-circular external pads	48
7.6	Copper planes in rigid PCB	49
7.7	Design considerations for the prevention of sliver and peelable	50
7.8	PCB surface finish	50
7.8.1	Metallization	50
7.8.2	Solder mask	51
8	Flex PCBs	52
8.1	Overview	52
8.2	Dynamic applications	52
8.3	PCB build-up	52
8.3.1	General	52
8.3.2	Dielectric materials	52
8.3.3	Copper cladding	53
8.3.4	Copper planes in flex PCB	53
8.4	Track design	54
8.5	Through holes	55
8.5.1	Annular ring	55
8.5.2	Vias and pads	56
8.5.3	Tear drop pad for flex PCB	56
8.6	Bending radius	57
8.6.1	Overview	57
8.6.2	General	57

8.7	Sculptured flex PCB	58
8.7.1	Overview.....	58
8.7.2	General.....	58
8.7.3	Copper foil dimensions for build-up.....	58
8.7.4	Connection finger	59
8.7.5	Through-holes	60
8.7.6	Bending radius.....	61
9	Rigid-flex PCBs.....	62
9.1	Overview	62
9.2	General.....	62
9.3	Build-up	63
9.4	Cover layer	64
9.5	Interface of rigid part and flexible part	64
9.6	Pads	64
10	Thermal rules and heat sinks	65
10.1	Overview	65
10.2	General requirements.....	65
10.3	Specific requirements for external heat sink	65
10.3.1	Overview.....	65
10.3.2	Construction of the interface between PCB and heat sink	65
10.3.3	Dimensional requirements.....	66
10.4	Specific requirements for internal heat sink	68
10.4.1	General.....	68
10.4.2	Cu thickness and type	68
10.4.3	CIC and Molybdenum inserts	69
10.4.4	Dimensional requirements.....	69
11	HDI PCBs.....	71
11.1	Overview	71
11.2	Justification.....	71
11.3	Microvia technology.....	71
11.4	Microvias	72
11.4.1	Build-up of microvia layers	72
11.4.2	Design of microvias	74
11.4.3	Pad design for microvia	74
11.4.4	Annular ring for microvias.....	75
11.5	Core PCB for HDI.....	75
11.5.1	General build-up.....	75

11.5.2	Annular ring on vias for fine pitch footprint	76
11.5.3	Track width and spacing on external layers.....	77
11.5.4	Track width and spacing on internal layers for impedance control and routing to AAD	77
11.5.5	Track width and spacing on internal layers for differential pair routing within the footprint of 1,0 mm pitch AAD.....	78
11.5.6	Aspect ratio of vias for footprint of AAD with 1 mm pitch.....	79
12	PCBs for high frequency applications.....	81
12.1	Material selection.....	81
12.2	Build-up of RF PCB	81
12.3	Embedded film resistors	81
12.4	Thickness of RF PCB	83
12.5	Track width and spacing.....	83
12.5.1	External layers	83
12.5.2	Internal Layers	84
12.6	Pad design.....	84
12.6.1	Pad dimensions	84
12.6.2	Non-functional pads.....	84
12.7	Surface finish.....	84
12.8	Profiled layers and vias	84
13	Electrical requirements for PCB design	86
13.1	Overview.....	86
13.2	General.....	87
13.3	PCB drying	87
13.4	Electrical characteristics	87
13.5	Floating metal	88
13.6	Current rating.....	88
13.6.1	Overview.....	88
13.6.2	Requirements for temperature increment.....	89
13.6.3	Requirements for the model IPC-2152 for current rating.....	89
13.6.4	Amendments to the model from IPC-2152	90
13.7	Provisions to prevent open circuit failure on critical tracks	91
13.7.1	Overview.....	91
13.7.2	Routing	92
13.8	Voltage rating	92
13.8.1	Overview.....	92
13.8.2	General requirements.....	92
13.8.3	Spacing on flex and rigid-flex laminate	94

13.8.4	Conformal coating	95
13.9	Double insulation design rules for critical tracks.....	96
13.9.1	Overview.....	96
13.9.2	Critical nets.....	96
13.9.3	Prevention of short circuit.....	96
13.10	Insulation distance of combined requirements on rigid PCB.....	101
13.11	Controlled impedance tracks.....	106
13.11.1	Definitions specific to controlled impedance.....	106
13.11.2	General rules.....	106
13.11.3	Microstrip and stripline.....	106
13.11.4	Line impedance termination for end-to-end configuration	107
13.11.5	Line impedance termination for multidrop configuration.....	107
13.12	Digital PCB	108
13.12.1	Overview.....	108
13.12.2	Zone management and routing	108
13.12.3	Criticality of digital signals	109
13.13	Analog PCB.....	110
13.13.1	Overview.....	110
13.13.2	Criticality of analog signals.....	110
13.13.3	Routing and shielding.....	111
13.14	Mixed analog-digital PCB.....	112
14	Design for assembly.....	113
14.1	Overview	113
14.2	General.....	113
14.3	Placement requirements	114
14.3.1	Conductive patterns.....	114
14.3.2	Components	115
14.3.3	Component pads	117
14.3.4	Fan out of SMT pads.....	118
14.3.5	Fan out of PTH	120
14.4	Specific requirements for fused tin-lead finish.....	121
14.5	Dimensional requirements for SMT foot print.....	121
14.5.1	Overview.....	121
14.5.2	General.....	122
14.5.3	Bipolar components.....	123
14.5.4	SOIC components	124
14.5.5	J-leaded components	125
14.5.6	LCC components.....	126

14.5.7	Flat pack components.....	128
14.5.8	AAD components.....	129
15	Design of test coupon	130
15.1	Design rules for test coupon.....	130
15.2	Test coupon design	130
Annex A	(normative) PCB definition dossier - DRD	133
A.1	DRD identification.....	133
A.1.1	Requirement identification and source document.....	133
A.1.2	Purpose and objective	133
A.2	Expected response.....	133
A.2.1	Scope and content.....	133
A.2.2	Special remarks	139
A.2.3	Example figures	139
Annex B	(normative) PCB manufacturing dossier – DRD	144
B.1	DRD identification.....	144
B.1.1	Requirement identification and source document.....	144
B.1.2	Purpose and objective	144
B.2	Expected response.....	144
B.2.1	Scope and content.....	144
B.2.2	Special remarks	145
Annex C	(informative) Example of capability list of PID	146
Annex D	(informative) Track current rating computation methodology	148
D.1	Introduction of the three models	148
D.1.1	Overview.....	148
D.1.2	Formulae for the three models.....	149
D.1.3	Example of current rating.....	150
D.2	Track current rating computation based on IPC-2152.....	150
D.3	Track current rating computation based on CNES/QFT/IN.0113	154
D.4	Track current rating computation based on IPC-2221A	158
Annex E	(informative) Example of calculation of PTH pad dimensions	162
Annex F	(informative) Prevention of resin starvation and cracks	164
F.1	Prevention of resin cracks.	164
F.2	Prevention of resin starvation	164
Annex G	(informative) Example of MRR checklist.....	166
Bibliography	170

Figures

Figure 3-1: Simplified build-up of HDI PCB 20

Figure 3-2: Projected peak-to-peak insulation distance 23

Figure 7-1: Example of automated fine pitch routing and possible improvements 45

Figure 7-2: Comparison between circular and oblong pads showing annular ring and the centre of the hole misregistered with the centre of the pad 48

Figure 7-3: Grid copper plane with openings 49

Figure 7-4: Example of peelable (left) and sliver (right) 50

Figure 8-1: Clearance of tracks on flex PCBs. 54

Figure 8-2: Tracks on flex, defining termination and bending zones. 55

Figure 8-3: Teardrop reinforcement of terminal pads in flex PCB. 56

Figure 8-4: Bending radius of assembled flex 57

Figure 8-5: Sculptured flex circuit..... 58

Figure 8-6: Build-up of sculptured flex circuit 59

Figure 8-7: Connection finger of sculptured flex circuit 60

Figure 8-8 Side view of a component hole for sculptured flex..... 61

Figure 9-1 Example of a build-up of a 6 layer symmetric rigid-flex 62

Figure 10-1: Lay out of heat sink and PCB 67

Figure 10-2: drilling holes and slots in internal heat sink..... 70

Figure 10-3: Angle of intersection of overlapping holes 70

Figure 11-1: Build-up of HDI PCBs with staggered (left) and stacked (right) microvia..... 72

Figure 11-2: Dimple on a microvia 74

Figure 11-3: Tear drop pad design..... 76

Figure 11-4: Example of routing two differential pair tracks between vias in a footprint of an AAD with 1,27 mm pitch. 78

Figure 11-5: Example of routing two differential pair tracks between vias in a footprint of an AAD with 1 mm pitch. 80

Figure 13-1: Cross section of PCB with insulation distances. 87

Figure 13-2: Example of double insulation by increasing distance in X,Y and by not superimposing copper on adjacent layers 100

Figure 13-3: Example of double insulation by increasing distances in X,Y and by using two insulators in Z direction..... 100

Figure 13-4: Edge coupled differential striplines 107

Figure 14-1: Illustration of surface pattern to adjacent surroundings 115

Figure 14-2: Illustration of component placing on PCB w.r.t. adjacent surrounding..... 116

Figure 14-3: Illustration of pad placing on PCB with respect to adjacent surroundings 118

Figure 14-4: Fan out from SMT pad to via 119

Figure 14-5: Example of point symmetric AAD footprint.....	120
Figure 14-6: Track width (l_c) ratio to PTH pad (D) diameter.	120
Figure 14-7: Track length (l_c) between soldering pad of PTH (D_1) and via pad (D_3).....	121
Figure 14-8: Illustration of bipolar component pads	123
Figure 14-9: Illustration of SOIC component pads	124
Figure 14-10: Illustration of J-leaded component pads	125
Figure 14-11: Illustration of LCC component pads	126
Figure 14-12: Illustration of FP and QFP component pads	128
Figure 14-13: Illustration of AAD component pads.....	129
Figure A-1 : Example of PCB mechanical layout.....	139
Figure A-2 : Example of a drilling drawing.....	140
Figure A-3 : Example of a table indicating as-designed plated hole diameters.....	141
Figure A-4 : Example of build-up data	142
Figure A-5 : Example of the archive file with CRC	143
Figure D-1 : Comparison between CNES and IPC-2152 current rating at 5°C increase.....	149
Figure D-2 : IPC-2152: Current rating [A] vs cross sectional area [mm^2] in double log scale	151
Figure D-3 : IPC-2152: Track width [mm] vs cross sectional area [mm^2].....	151
Figure D-4 : IPC-2152: Current rating based on Figure D-2, range 0-25 A.....	152
Figure D-5 : IPC-2152: Current rating based on Figure D-2, range 0-10 A.....	152
Figure D-6 : IPC-2152: Current rating based on Figure D-2, range 0-5 A.....	153
Figure D-7 : IPC-2152: Current rating based on Figure D-2, range 0-2 A.....	153
Figure D-8 : CNES/QFT/IN.0113: Current rating [A] vs cross sectional area [mm^2] in double log scale.....	155
Figure D-9 : CNES/QFT/IN.0113: Track width [mm] vs cross sectional area [mm^2].....	155
Figure D-10 : CNES/QFT/IN.0113: Current rating based on Figure D-8, range 0-25 A	156
Figure D-11 : CNES/QFT/IN.0113: Current rating based on Figure D-8, range 0-10 A	156
Figure D-12 : CNES/QFT/IN.0113: Current rating based on Figure D-8, range 0-5 A	157
Figure D-13 : CNES/QFT/IN.0113: Current rating based on Figure D-8, range 0-2 A	157
Figure D-14 : IPC-2221A: Current rating [A] vs cross sectional area [mm^2] in double log scale	159
Figure D-15 : IPC-2221A: Track width [mm] vs cross sectional area [mm^2].....	159
Figure D-16 : IPC-2221A: Current rating based on Figure D-14, range 0-25 A	160
Figure D-17 : IPC-2221A: Current rating based on Figure D-14, range 0-10 A	160
Figure D-18 : IPC-2221A: Current rating based on Figure D-14, range 0-5 A	161
Figure D-19 : IPC-2221A: Current rating based on Figure D-14, range 0-2 A	161
Figure E-1 : PCB manufacturing tolerances for registration and annular ring for HDI PCB .	162
Figure E-2 : PCB manufacturing tolerances for registration and annular ring for rigid-flex sequential PCB	163

Tables

Table 6-1: Characteristics of some example dielectric materials for laminates.....	32
Table 7-1: As-designed versus as-manufactured copper foil thickness	36
Table 7-2: Example of worst case as-manufactured insulation distance for laminate with double-sided copper cladding.....	39
Table 7-3: Tolerance on track width and spacing of internal and external layers	42
Table 7-4: Minimum as-manufactured track width and spacing for external layers as a function of copper thickness.....	43
Table 7-5: Minimum as-manufactured track width and spacing for internal layers as a function of copper thickness.....	44
Table 8-1: Minimum as-manufactured dimensions of sculptured flex conductor	59
Table 12-1: Minimum spacing and width as-designed for RF elements on external layers ...	84
Table 13-1: Legend of terms	86
Table 13-2: Current overload limits	88
Table 13-3: Minimum insulation distance as function of voltage on as-manufactured PCB for rigid laminate.	94
Table 13-4: Minimum insulation distance as function of voltage on as-manufactured PCB for flex laminate.....	95
Table 13-5: Minimum double insulation distance as function of voltage on as-manufactured PCB for rigid laminate.....	98
Table 13-6: Minimum double insulation distance as function of voltage on as-manufactured PCB for flex laminate.	98
Table 13-7: Minimum insulation distances on rigid PCB as function of all combined requirements (<i>part 1 of 4</i>).....	102
Table 14-1: Minimum distance as-manufactured of the surface pattern to the adjacent surroundings	114
Table 14-2: Minimum distance as-manufactured of components to adjacent surroundings	116
Table 14-3: Minimum distance as-manufactured to component pads.....	117
Table 14-4: Minimum track length to component pads	120
Table 14-5 Legend for dimensions of components and footprint	122
Table 14-6 As-manufactured pad sizes for bipolar components	123
Table 14-7: As-manufactured pad sizes for SOIC components	124
Table 14-8: As-manufactured pad sizes for J-leaded components	125
Table 14-9: As-manufactured pad sizes for LCC components.....	127
Table 14-10: As-manufactured pad sizes for FP and QFP components.....	128
Table 14-11: As-designed pad diameter for AAD components	129

Table C-1 : Example of technical capabilities of PCB manufacturer as specified in the PID146